规格书编号 ：HDBF07625A24SP01

SPEC NO：HDBF07625A24SP01

产品规格书
SPECIFICATION

CUSTOMER 客 户：

PRODUCT 产 品：SAW FILTER

MODEL NO 型 号：HDBF07625A24 SMD-24

PREPARED 编 制：俞虹 CHECKED 审 核：邓攀

APPROVED 批 准：倪山林 D A T E 日 期：2009-04-21

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子有限公司

Shoulder Electronics Limited

更改历史记录
History Record

更改日期 Date	规格书编号 Spec. No.	产品型号 Part No.	客户产品型号 Customer No.	更改内容描述 Modify Content	备注 Remark
2009.04.21	HDBF07625A24SP01	HDBF07625A24			Ver.01(Original)

1. SCOPE

This specification shall cover the characteristics of SAW filter with HDBF07625A24 used for the page system.

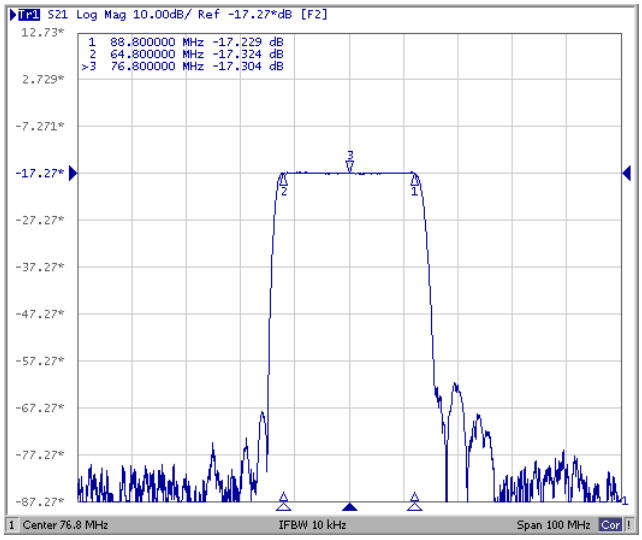
2. ELECTRICAL SPECIFICATION

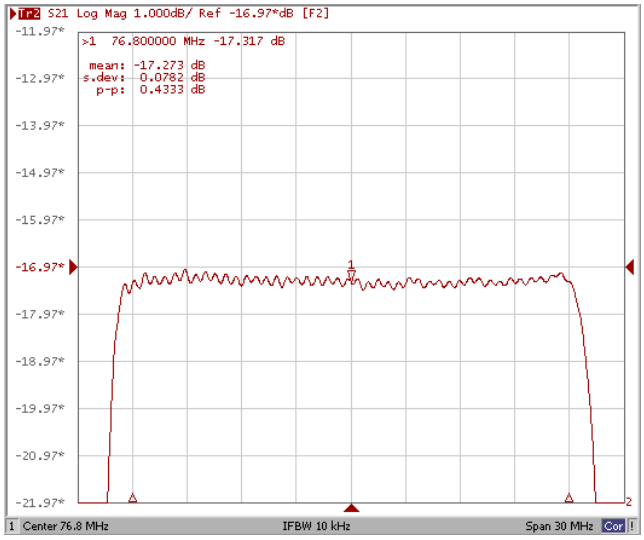
Maximum incident power in passband	+10dBm
Max.DC voltage between any 2 terminals	30VDC
Storage temperature range	-40℃ to +85℃
Operation temperature range	-40℃ to +85℃

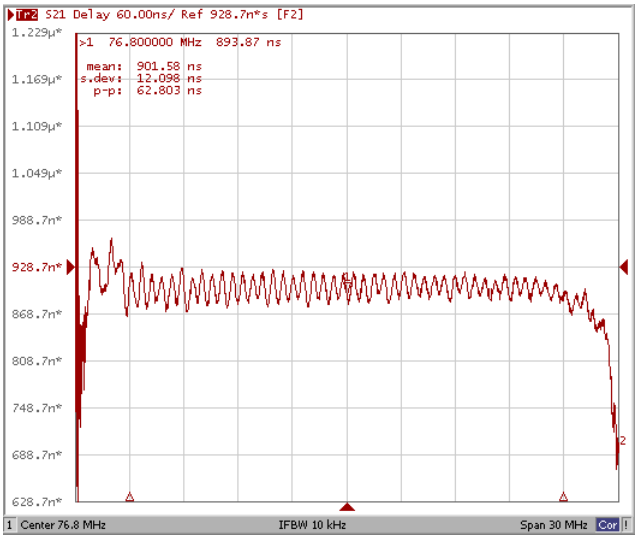
Electronic Characteristics

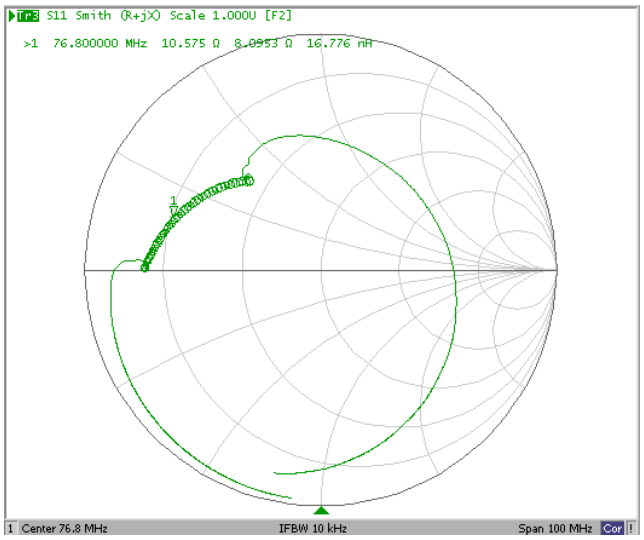
Parameter	Min.	Typical.	Max.	Unit
Center Frequency	76.65	76.8	76.95	MHz
Insertion loss	-	17.3	20	dB
-1.2dB Bandwidth	24.8	25.7	-	MHz
-3dB Bandwidth	25	26.4		MHz
-10dB Bandwidth		27.77		MHz
-20dB Bandwidth		28.89		MHz
-35dB Bandwidth		30	31	MHz
Passband Variation		0.5	1.2	dB
Absolute Delay		0.9	1.2	us
Group delay Variation (F0 +/- 12MHz)		60	120	ns
Phase Linearity (F0 +/- 12MHz)		6	9	deg
Ultimate Rejection (Over F0 +/- 20MHz)	42	44		dB
Temperature Coefficient		-86		ppm/°C
Package Size	SMD 13.3*6.5			

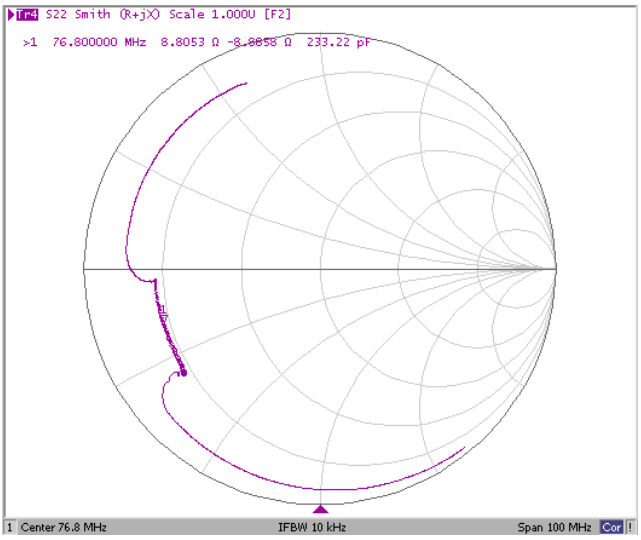
Typical frequency response



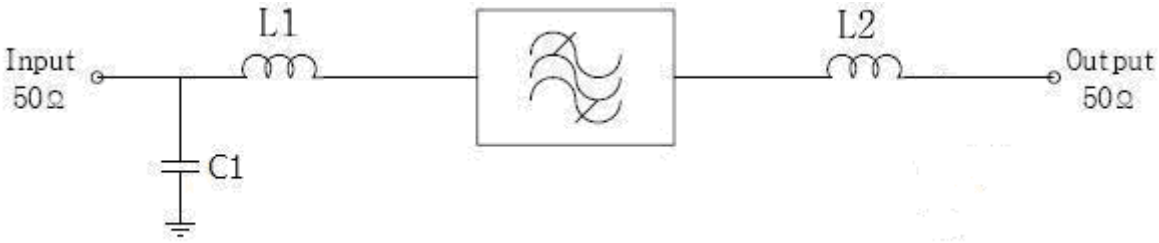






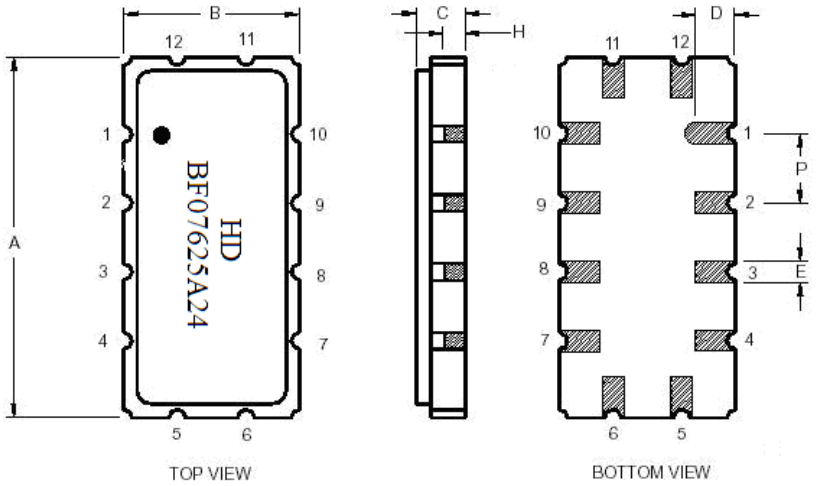


3. TEST CIRCUIT



L1 = 68 nH , L2 = 56 nH
C1 = 51pF
* Component values may change depending on board layout.

4.DIMENSION



Dimension	mm		
	min	typ	max
A	13.1	13.3	13.5
B	6.3	6.5	6.7
C	1.21	1.36	1.51
D		1.5	
E		0.8	
H	0.72	0.76	0.80
P		2.54	

Pin Configuration	
11	Input
5	Output
Other	Ground

5. ENVIRONMENTAL CHARACTERISTICS

5-1 Temperature cycling

Subject the device to a low temperature of -40℃for 30 minutes. Following by a high temperature of +25℃ for 5 Minutes and a higher temperature of +85℃ for 30 Minutes. Then release the device into the room conditions for 1 to 2 hours prior to the measurement. It shall meet the specifications in table 1.

5-2 Resistance to solder heat

Submerge the device terminals into the solder bath at 260℃ ±5℃ for 10±1 sec. Then release the device into the room conditions for 4 hours. It shall meet the specifications in table 1.

5-3 Solderability

Submerge the device terminals into the solder bath at 245℃ ±5℃ for 5s, More than 95% area of the soldering pad must be covered with new solder. It shall meet the specifications in table 1.

5-4 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1 m 3 times. the filter shall fulfill the specifications in table 1.

5-5 Vibration

Subject the device to the vibration for 2 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 hz. The filter shall fulfill the specifications in table 1.

6. REMARK

6.1 Static voltage

Static voltage between signal load & ground may cause deterioration &destruction of the component. Please avoid static voltage.

6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.